

12-23-2003

Form PTO-1595

(Rev. 03/01)

OMB No. 0651-0027 (exp. 5/31/2002)



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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

Shin Seung Park

12.12.03

Additional name(s) of conveying party(ies) attached?

☐

Yes

☒

No

3. Nature of Conveyance:

☒

Assignment

☐

Merger

☐

Security Agreement

☐

Change of Name

☐

Other

Execution Dates: August 25, 2003

2. Name and address of receiving party(ies)

Name: HYNIX SEMICONDUCTOR INC.

Address:

San 136-1, Ami-Ri
Bubal-Uep
Ichon-shi

City: Kyungki-Do

Country Republic of Korea Zip:

Additional name(s) & address(es) attached:

☐

Yes

☒

No

4. Application number(s) or patent number(s):

10735228

If this document is being filed together with a new application, the execution date of the new application is: December 12, 2003

A. Patent Application No.:

B. Patent No.(s):

Additional numbers attached?

☐

Yes

☒

No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Michael R. Hull

Client/Matter No.: 29936/39847/US

Address:

6300 Sears Tower
233 S. Wacker Drive

City:

Chicago

State:

IL

Zip:

60606-6357

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41)

\$ 40.00

☒

Enclosed

☐

Authorized to be charged to deposit account

8. Deposit account number:

13-2855

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Sandip H. Patel, 43,848

Name of Person Signing

Signature

December 12, 2003

Date

Total number of pages including cover sheet, attachments, and documents: 3

17548 U.S. PTO
10735228

121203

ASSIGNMENT

Serial No:

Filed:

Title: **METHOD OF FORMING METAL LINE OF SEMICONDUCTOR
DEVICE**

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assign(s) to Hynix Semiconductor Inc., of San 136-1, Ami-Ri, Bubal-Uep, Ichon-Shi, Kyungki-Do, Republic of Korea, (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, and in said application and any and all other U.S. applications which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States which may be obtained on any of said applications, and in any reissue or extension thereof.

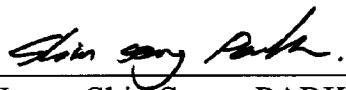
The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee. The undersigned also hereby authorizes the attorneys of Marshall, Gerstein & Borun to insert the filing date and serial number of this application in the blanks above when they become known.

The undersigned warrant(s) themselves (himself/herself) to be the owners (owner) of the interest herein assigned and to have the right to make this assignment and further warrant(s) that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agree(s), upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application that said assignee, its successors or assigns, may deem necessary or expedient, and for the aforesaid consideration the undersigned further agree(s) upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent in the United States and to vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

SIGNED:

Date: August 25, 2003


Name: Shin Seung PARK